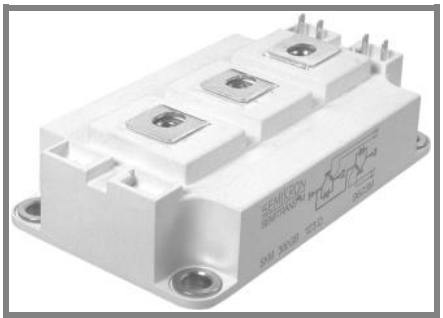
SKM 150GB123D



SEMITRANS® 3

IGBT Modules

SKM 150GB123D

SKM 150GAL123D

Features

- MOS input (voltage controlled)
- N channel, Homogeneous Si
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- Latch-up free
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- Isolated copper baseplate using DCB Direct Copper Bonding
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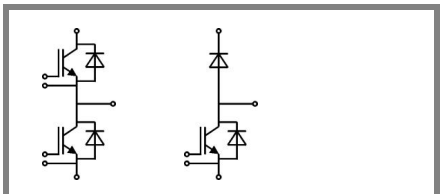
Typical Applications

- AC inverter drives
- UPS

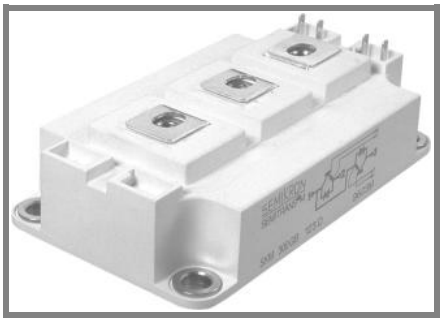


GB **GAL**

Absolute Maximum Ratings			T_c = 25 °C, unless otherwise specified	
Symbol	**Conditions**		**Values**	**Units**
IGBT				
V_{CES}	T_j = 25 °C		1200	V
I_C	T_j = 150 °C	T_{case} = 25 °C	150	A
		T_{case} = 80 °C	110	A
I_{CRM}	I_{CRM}=2xI_{Cnom}		200	A
V_{GES}			± 20	V
t_{psc}	V_{CC} = 600 V; $V_{GE} \leq$ 20 V; V_{CES} < 1200 V	T_j = 125 °C	10	µs
Inverse Diode				
I_F	T_j = 150 °C	T_{case} = 25 °C	150	A
		T_{case} = 80 °C	100	A
I_{FRM}	I_{FRM}=2xI_{Fnom}		200	A
I_{FSM}	t_p = 10 ms; sin.	T_j = 150 °C	1100	A
Freewheeling Diode				
I_F	T_j = 150 °C	T_{case} = 25 °C	200	A
		T_{case} = 80 °C	135	A
I_{FRM}			300	A
I_{FSM}	t_p = 10 ms; sin.	T_j = 150 °C	1440	A
Module				
$I_{t(RMS)}$			500	A
T_{vj}			- 40 ... + 150	°C
T_{stg}			-40 ... + 125	°C
V_{isol}	AC, 1 min.		2500	V

Characteristics			T_c = 25 °C, unless otherwise specified			
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Units**
IGBT						
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 4 mA		4,5	5,5	6,5	V
I_{CES}	V_{GE} = 0 V, V_{CE} = V_{CES}	T_j = 25 °C		0,1	0,3	mA
		T_j = 125 °C				mA
V_{CE0}		T_j = 25 °C		1,4	1,6	V
		T_j = 125 °C		1,6	1,8	V
r_{CE}	V_{GE} = 15 V	T_j = 25°C		11	14	mΩ
		T_j = 125°C		15	19	mΩ
$V_{CE(sat)}$	I_{Cnom} = 100 A, V_{GE} = 15 V	T_j = °$C_{chiplev.}$		2,5	3	V
C_{ies}	V_{CE} = 25, V_{GE} = 0 V	f = 1 MHz		6,5	8,5	nF
C_{oes}				1	1,5	nF
C_{res}				0,5	0,6	nF
Q_G	V_{GE} = -8V - +20V			1000		nC
R_{Gint}	T_j = °C			2,5		Ω
$t_{d(on)}$	R_{Gon} = 6,8 Ω	V_{CC} = 600V		160	320	ns
t_r		I_{Cnom}= 100A		80	160	ns
E_{on}		T_j = 125 °C		13		mJ
$t_{d(off)}$	R_{Goff} = 6,8 Ω	V_{GE} = ± 15V		400	520	ns
t_f				70	100	ns
E_{off}				11		mJ
$R_{th(j-c)}$	per IGBT				0,15	K/W

SKM 150GB123D



SEMITRANS® 3

IGBT Modules

SKM 150GB123D

SKM 150GAL123D

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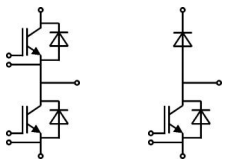


GB **GAL**

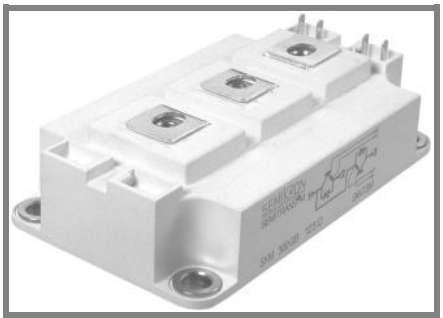
Characteristics

Symbol	Conditions		min.	typ.	max.	Units
Inverse Diode						
$V_F = V_{EC}$	I_{Fnom} = 100 A; V_{GE} = 0 V	T_j = 25 °C$_{chiplev.}$		2	2,5	V
		T_j = 125 °C$_{chiplev.}$		1,8		V
V_{F0}		T_j = 25 °C		1,1	1,2	V
		T_j = 125 °C				V
r_F		T_j = 25 °C		9	13	mΩ
		T_j = 125 °C				mΩ
I_{RRM}	I_{Fnom} = 100 A	T_j = 125 °C		50		A
Q_{rr}	di/dt = 1000 A/µs			5		µC
E_{rr}	V_{GE} = 0 V; V_{CC} = 600 V					mJ
$R_{th(j-c)D}$	per diode				0,3	K/W
Freewheeling Diode						
$V_F = V_{EC}$	I_{Fnom} = 150 A; V_{GE} = 0 V	T_j = 25 °C$_{chiplev.}$		2	2,5	V
		T_j = 125 °C$_{chiplev.}$		1,8		V
V_{F0}		T_j = 25 °C		1,1	1,2	V
		T_j = 125 °C				V
r_F		T_j = 25 °C		6	8,7	V
		T_j = 125 °C				V
I_{RRM}	I_{Fnom} = 100 A	T_j = 25 °C		40		A
Q_{rr}				5		µC
E_{rr}	V_{GE} = 0 V; V_{CC} = 600 V					mJ
$R_{th(j-c)FD}$	per diode				0,25	K/W
Module						
L_{CE}				15	20	nH
$R_{CC'+EE'}$	res., terminal-chip	T_{case}= 25 °C		0,35		mΩ
		T_{case}= 125 °C		0,5		mΩ
$R_{th(c-s)}$	per module				0,038	K/W
M_s	to heat sink M6		3		5	Nm
M_t	to terminals M6		2,5		5	Nm
w					325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.

SKM 150GB123D



SEMITRANS® 3

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SKM 150GB123D

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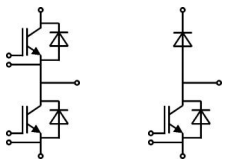


GB **GAL**

Z_{th} Symbol	Conditions	Values	Units
$Z_{th(j-c)I}$			
R_i	i = 1	105	mk/W
R_i	i = 2	35	mk/W
R_i	i = 3	8	mk/W
R_i	i = 4	2	mk/W
tau_i	i = 1	0,03	s
tau_i	i = 2	0,03	s
tau_i	i = 3	0,0014	s
tau_i	i = 4	0,0001	s
$Z_{th(j-c)D}$			
R_i	i = 1	210	mk/W
R_i	i = 2	70	mk/W
R_i	i = 3	16	mk/W
R_i	i = 4	4	mk/W
tau_i	i = 1	0,0623	s
tau_i	i = 2	0,0083	s
tau_i	i = 3	0,003	s
tau_i	i = 4	0,0002	s

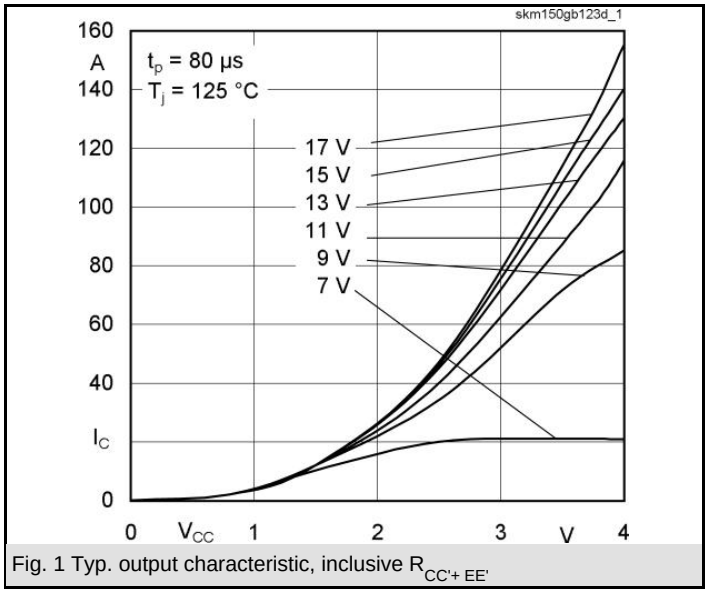


Fig. 1 Typ. output characteristic, inclusive $R_{CC'+ EE'}$

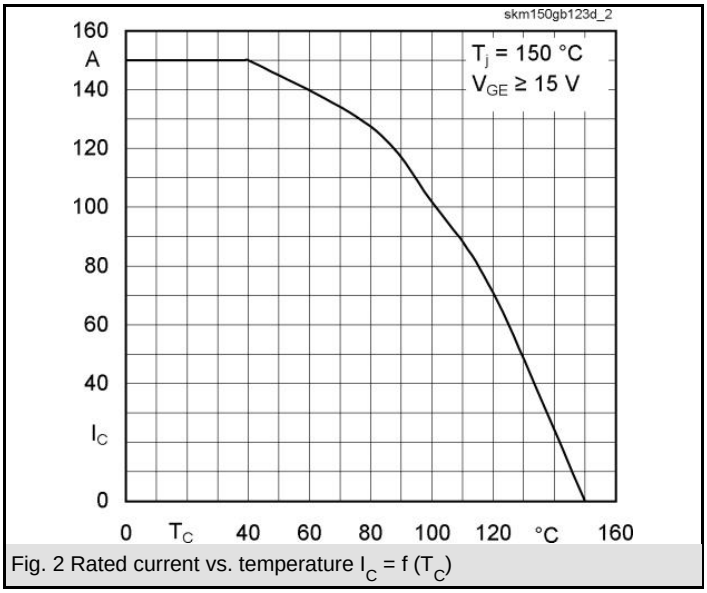


Fig. 2 Rated current vs. temperature $I_C = f(T_C)$

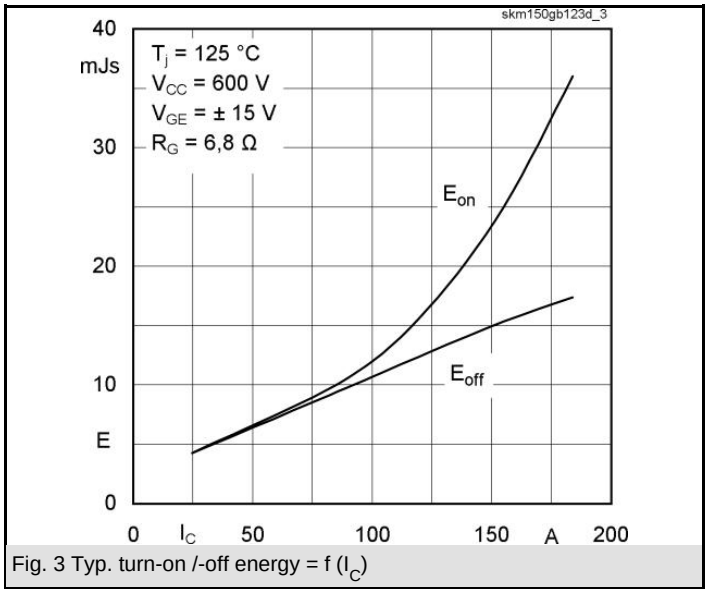


Fig. 3 Typ. turn-on /-off energy = f (I_C)

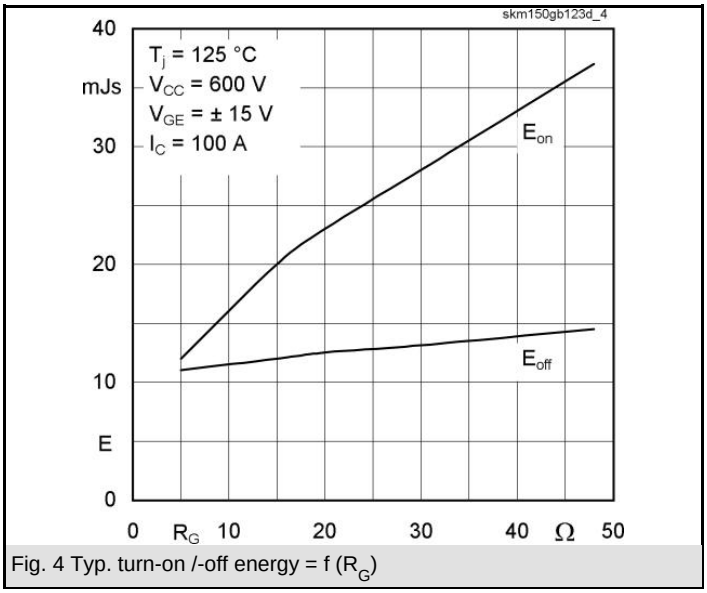


Fig. 4 Typ. turn-on /-off energy = f (R_G)

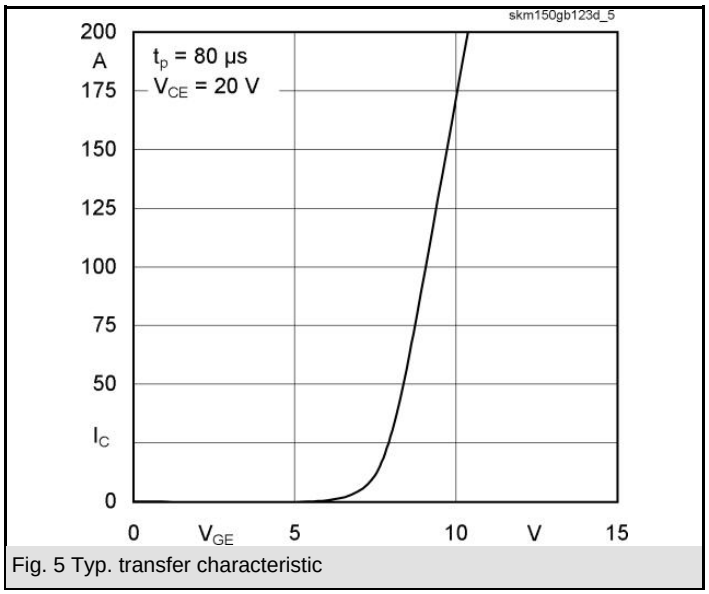


Fig. 5 Typ. transfer characteristic

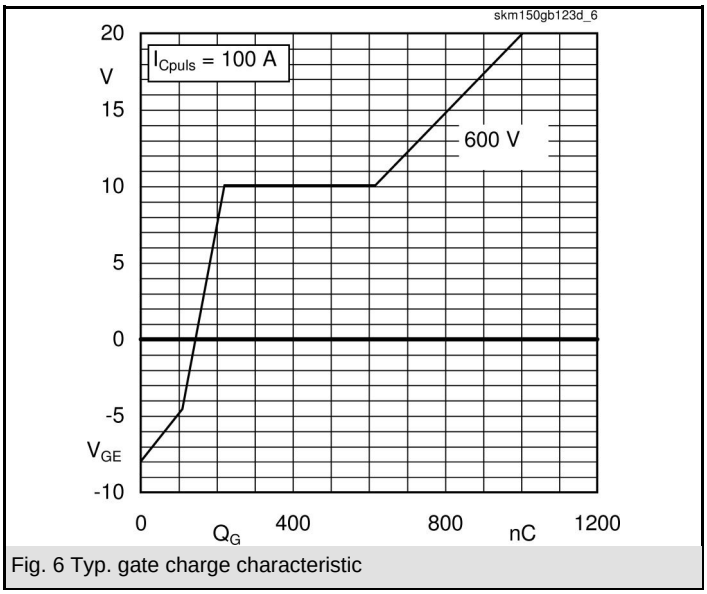


Fig. 6 Typ. gate charge characteristic

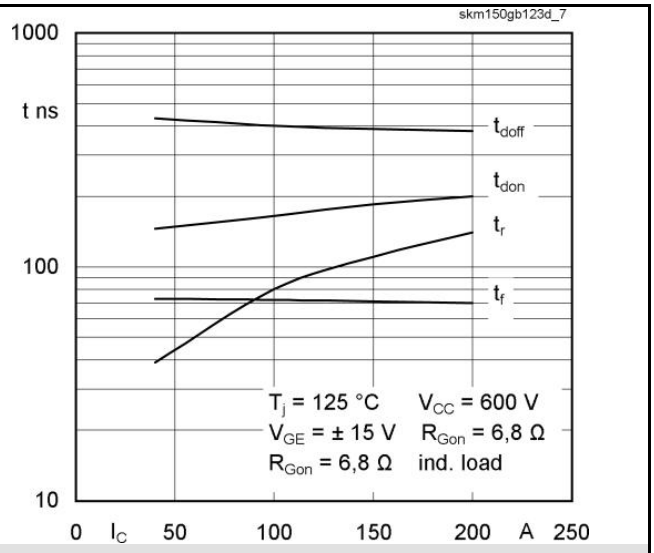


Fig. 7 Typ. switching times vs. I_C

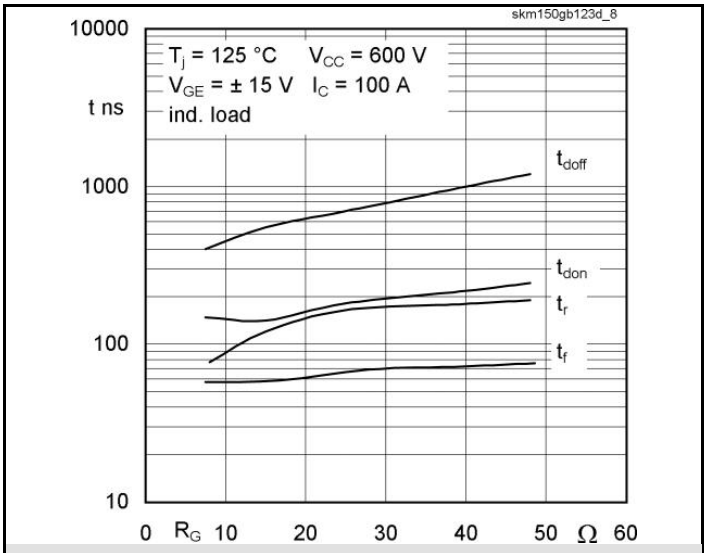


Fig. 8 Typ. switching times vs. gate resistor R_G

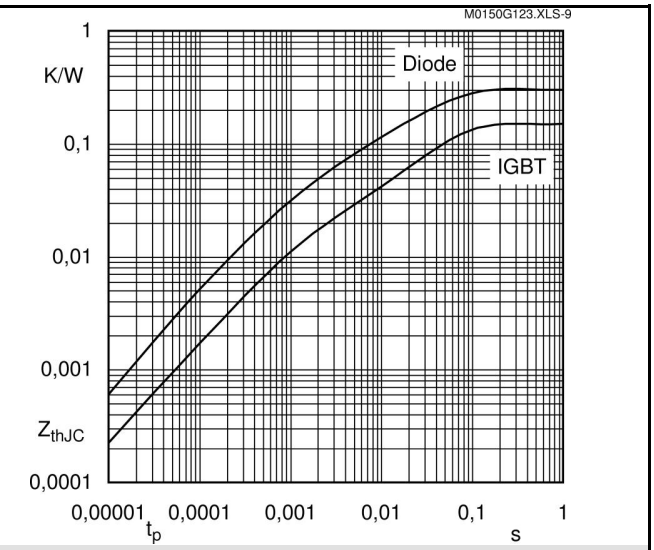


Fig. 9 Transient thermal impedance of IGBT

$Z_{thp(j-c)} = f(t_p)$; $D = t_p/t_c = t_p * f$

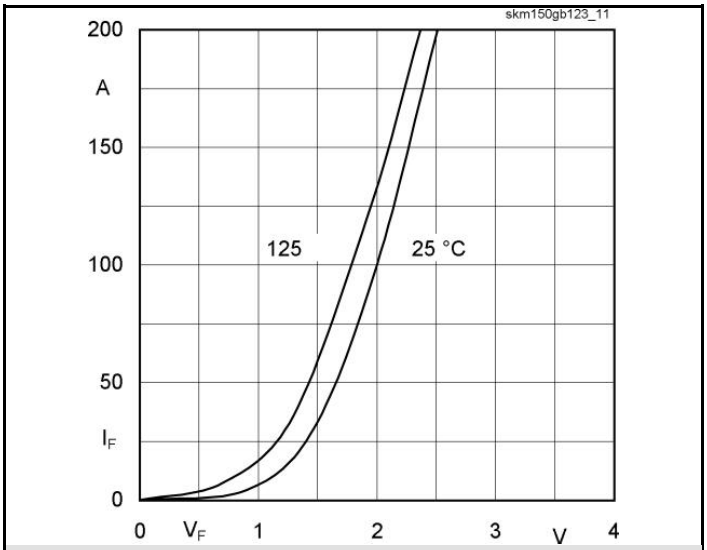


Fig. 10 Transient thermal impedance of FWD

$Z_{thp(j-c)} = f(t_p)$; $D = t_p/t_c = t_p * f$

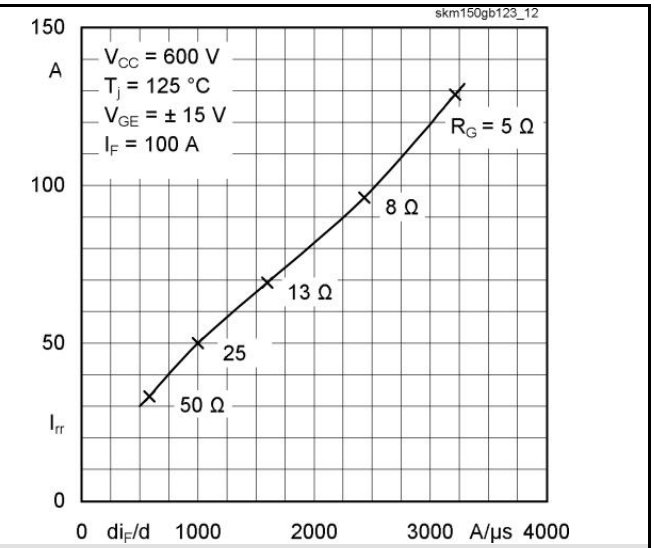


Fig. 11 CAL diode forward characteristic

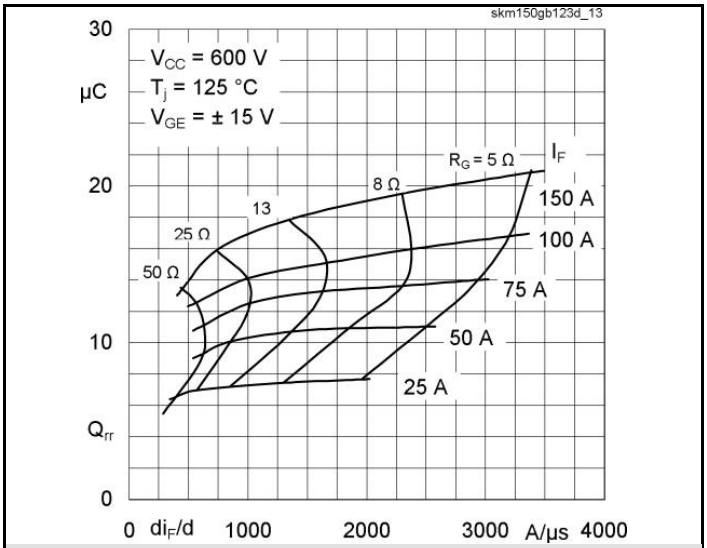
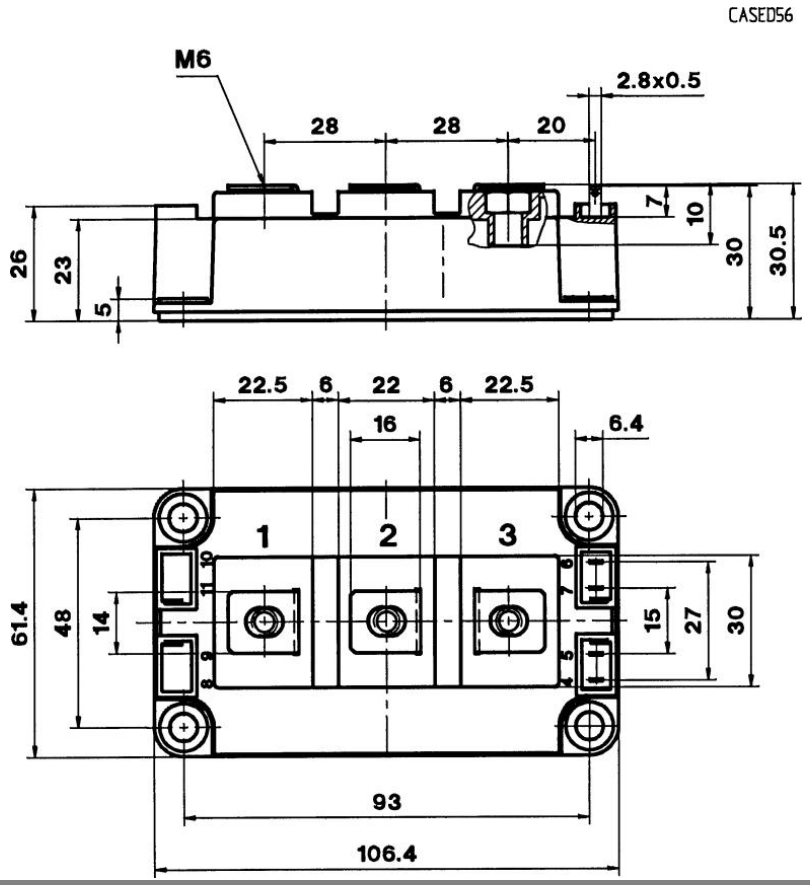
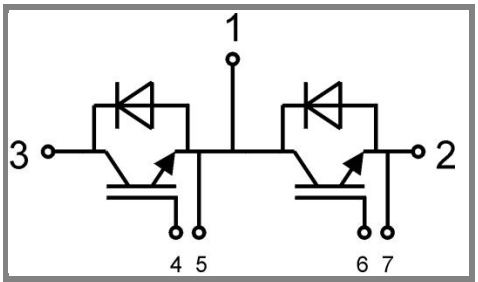


Fig. 12 Typ. CAL diode peak reverse recovery current

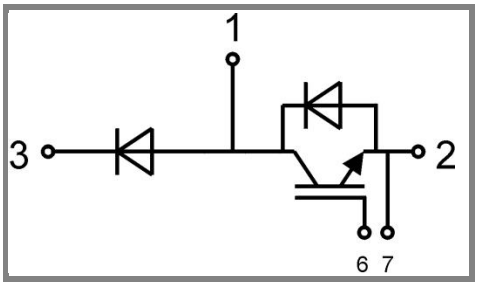
UL Recognized File no. E63 532



Case D 56



GB Case D 56



GAL Case D 57 (➞ D 56)

